



FDP10N60NZ / FDPF10N60NZ

N-Channel MOSFET

600V, 10A, 0.75Ω

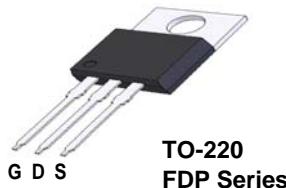
Features

- $R_{DS(on)} = 0.64\Omega$ (Typ.) @ $V_{GS} = 10V$, $I_D = 5A$
- Low Gate Charge (Typ. 23nC)
- Low C_{rss} (Typ. 10pF)
- Fast Switching
- 100% Avalanche Tested
- Improved dv/dt Capability
- ESD Improved Capability
- RoHS compliant

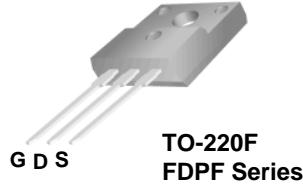
Description

These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology.

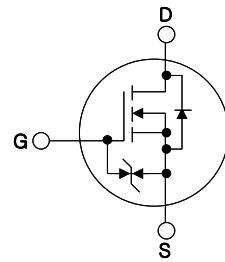
This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficient switched mode power supplies and active power factor correction.



TO-220
FDP Series



TO-220F
FDPF Series
(potted)



MOSFET Maximum Ratings $T_C = 25^\circ C$ unless otherwise noted*

Symbol	Parameter		FDP10N60NZ	FDPF10N60NZ	Units
V_{DSS}	Drain to Source Voltage		600		V
V_{GSS}	Gate to Source Voltage		± 25		V
I_D	Drain Current	- Continuous ($T_C = 25^\circ C$)	10	10*	A
		- Continuous ($T_C = 100^\circ C$)	6	6*	
I_{DM}	Drain Current	- Pulsed	(Note 1)	40	40*
E_{AS}	Single Pulsed Avalanche Energy		550		mJ
I_{AR}	Avalanche Current		10		A
E_{AR}	Repetitive Avalanche Energy		18.5		mJ
dv/dt	Peak Diode Recovery dv/dt		10		V/ns
P_D	Power Dissipation	($T_C = 25^\circ C$)	185	38	W
		- Derate above $25^\circ C$	1.5	0.3	$^\circ C/W$
T_J, T_{STG}	Operating and Storage Temperature Range		-55 to +150		$^\circ C$
T_L	Maximum Lead Temperature for Soldering Purpose, 1/8" from Case for 5 Seconds		300		$^\circ C$

*Drain current limited by maximum junction temperature

Thermal Characteristics

Symbol	Parameter	FDP10N60NZ	FDPF10N60NZ	Units
$R_{\theta JC}$	Thermal Resistance, Junction to Case	0.68	3.3	$^\circ C/W$
$R_{\theta CS}$	Thermal Resistance, Case to Sink Typ	0.5	-	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	62.5	62.5	

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDP10N60NZ	FDP10N60NZ	TO-220	-	-	50
FDPF10N60NZ	FDPF10N60NZ	TO-220F	-	-	50

Electrical Characteristics $T_C = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
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Off Characteristics

BV_{DSS}	Drain to Source Breakdown Voltage	$I_D = 250\mu\text{A}, V_{GS} = 0\text{V}, T_J = 25^\circ\text{C}$	600	-	-	V
$\Delta \text{BV}_{\text{DSS}}$ ΔT_J	Breakdown Voltage Temperature Coefficient	$I_D = 250\mu\text{A}$, Referenced to 25°C	-	0.6	-	$\text{V}/^\circ\text{C}$
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 600\text{V}, V_{GS} = 0\text{V}$	-	-	1	μA
		$V_{DS} = 480\text{V}, T_C = 125^\circ\text{C}$	-	-	10	
I_{GSS}	Gate to Body Leakage Current	$V_{GS} = \pm 25\text{V}, V_{DS} = 0\text{V}$	-	-	± 10	μA

On Characteristics

$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250\mu\text{A}$	3.0	-	5.0	V
$R_{DS(\text{on})}$	Static Drain to Source On Resistance	$V_{GS} = 10\text{V}, I_D = 5\text{A}$	-	0.64	0.75	Ω
g_{FS}	Forward Transconductance	$V_{DS} = 20\text{V}, I_D = 5\text{A}$	-	14	-	S

Dynamic Characteristics

C_{iss}	Input Capacitance	$V_{DS} = 25\text{V}, V_{GS} = 0\text{V}$ $f = 1\text{MHz}$	-	1110	1475	pF
C_{oss}	Output Capacitance		-	130	175	pF
C_{rss}	Reverse Transfer Capacitance		-	10	15	pF
Q_g	Total Gate Charge at 10V	$V_{DS} = 480\text{V}, I_D = 10\text{A}$	-	23	30	nC
Q_{gs}	Gate to Source Gate Charge	$V_{GS} = 10\text{V}$	-	6	-	nC
Q_{gd}	Gate to Drain "Miller" Charge		-	8	-	nC

Switching Characteristics

$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = 300\text{V}, I_D = 10\text{A}$ $R_G = 25\Omega$	-	25	60	ns
t_r	Turn-On Rise Time		-	50	110	ns
$t_{d(off)}$	Turn-Off Delay Time		-	70	150	ns
t_f	Turn-Off Fall Time		-	50	110	ns

Drain-Source Diode Characteristics

I_S	Maximum Continuous Drain to Source Diode Forward Current	-	-	10	A
I_{SM}	Maximum Pulsed Drain to Source Diode Forward Current	-	-	40	A
V_{SD}	Drain to Source Diode Forward Voltage	$V_{GS} = 0\text{V}, I_{SD} = 10\text{A}$	-	-	1.4
t_{rr}	Reverse Recovery Time	$V_{GS} = 0\text{V}, I_{SD} = 10\text{A}$	-	300	-
Q_{rr}	Reverse Recovery Charge	$dI_F/dt = 100\text{A}/\mu\text{s}$	-	2	-

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature
2. $L = 11\text{mH}, I_{AS} = 10\text{A}, V_{DD} = 50\text{V}, R_G = 25\Omega$, Starting $T_J = 25^\circ\text{C}$
3. $I_{SD} \leq 10\text{A}, dI/dt \leq 200\text{A}/\mu\text{s}, V_{DD} \leq \text{BV}_{\text{DSS}}$, Starting $T_J = 25^\circ\text{C}$
4. Pulse test: Pulse width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$
5. Essentially Independent of Operating Temperature Typical Characteristics

Typical Performance Characteristics

Figure 1. On-Region Characteristics

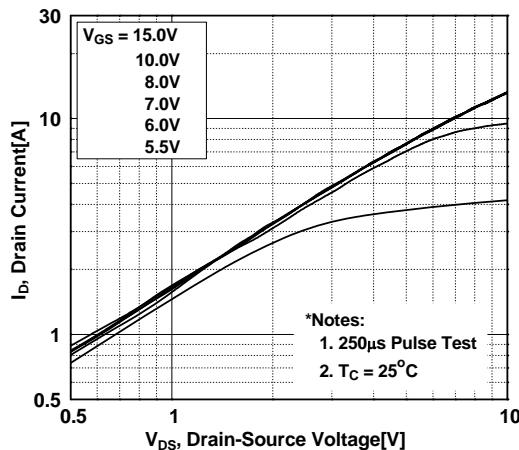


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

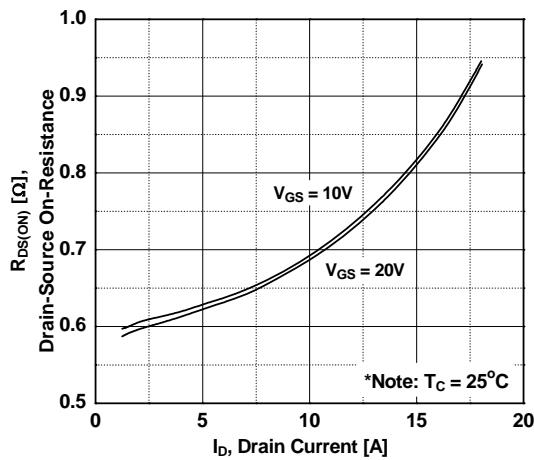


Figure 5. Capacitance Characteristics

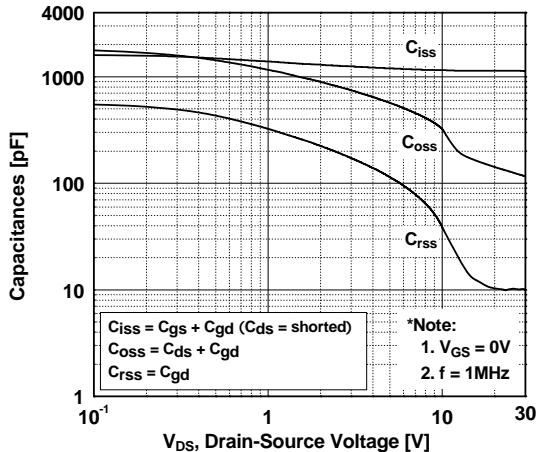


Figure 2. Transfer Characteristics

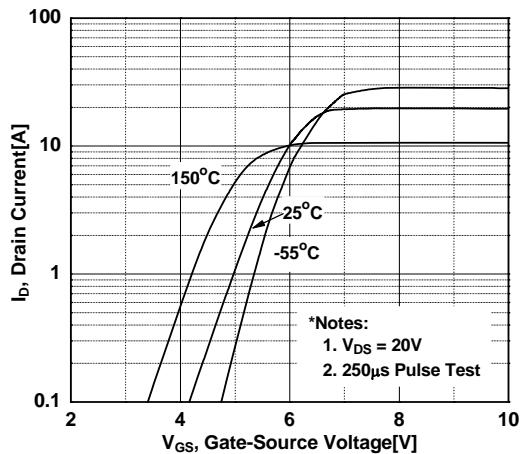


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

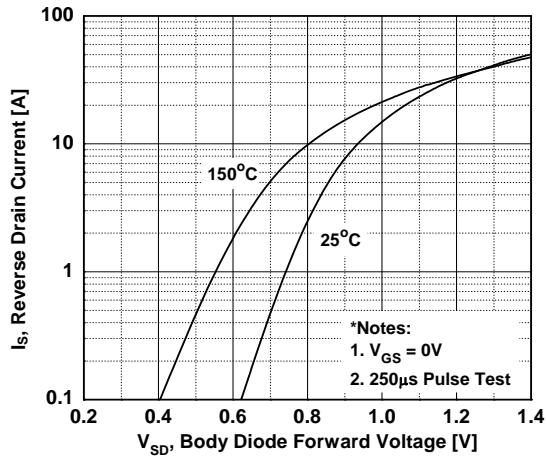


Figure 6. Gate Charge Characteristics

